

Abstract

Laminate Peeling Method, Laminate, and Laminate Production Method

A laminate debonding method includes a first step of producing a laminate 10 by joining a first substrate 11 formed of a semiconductor-forming substrate to a second substrate 12 formed of a support substrate which allows passage of infrared laser light, by the mediation of a first adhesive layer 13 provided on the first substrate and a second adhesive layer 14 provided on the second substrate 12, wherein the first adhesive layer 13 is an adhesive layer obtained by curing an adhesive (A) containing a component which is cured through hydrosilylation, and the second adhesive layer 14 is an adhesive layer which is obtained by use of an adhesive (B) formed of a polymer adhesive having an aromatic ring in at least one of a main chain and a side chain and which allows passage of infrared laser light; and a second step of irradiating the laminate with infrared laser light from a second substrate side for debonding the second substrate at the interface between the first and second adhesive layers.

FIG. 1